flow system, preventing the leakage of a toxic substance to the outside. For example, Japanese Patent Laid-Open No. 2008-166709 describes such a technology.

[0004]

However, in the conventional substrate polishing apparatus, it is necessary to improve tightness and enhance an exhaust volume in each portion of the apparatus, so that it becomes necessary to make significant design changes. Therefore, it has been desired to develop an apparatus capable of preventing the diffusion of a hazardous gas effectively without a significant design change.

[0005]

A substrate polishing apparatus of one embodiment includes a substrate holding portion that holds a substrate and presses the substrate against a polishing table to polish the substrate; a pad cooling nozzle for cooling a polishing pad that polishes the substrate; and a local exhaust mechanism whose intake head is disposed near the pad cooling nozzle, in which the intake head is disposed on a downstream side of the pad cooling nozzle in a rotation direction of the polishing table.

[0006]

A substrate polishing apparatus of another embodiment includes a rotating polishing table, a substrate holding portion that holds a substrate and presses the substrate against the polishing table to polish the substrate, and a local exhaust mechanism whose intake head is disposed near the substrate holding portion, in which the intake head is disposed on a downstream side of the substrate holding portion in a rotation direction of the polishing table.

BRIEF DESCRIPTION OF DRAWINGS

[0007]

FIG. 1 is a plan view illustrating a whole configuration of a substrate processing apparatus in a first embodiment;

[0008]

FIG. 2 is a perspective view illustrating a structure of a swing transporter in the first embodiment;

[0009]

FIG. 3(A) is a plan view illustrating a cleaning portion in the first embodiment, and FIG. 3(B) is a side